IPC ASSOCIATION CONNECT ELECTRONICS INDUST.	© Copyright 2005. IPC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both nternational and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				als and Mfg Information				
upplier Infor	mation				•									
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
onsemi											2025-09-14			
Contact Name			Title - Contact			1	Phone - Contact*				Email - Contact*			
Product-Env-Ste	wards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
uthorized Repre	esentative*		Title - Representative			I	Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Reque	ester Item Number	or Item Number Mfr Item Number Mfr Item Name NRVTS5100ETFSTW 5A 100V Trench of G		Mfr Item Name			Effective Date	Version	N	Manufacturing Site	W	eight*	UOM	Unit Type
				5A 100V Trench So	chottky u8FL	,	2025-09-14 MY1		Л Ү1	32	.25	mg	Each	
Ianufacturin	g Proccess Informatio	on												
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD			STD-020 MS	L Rating	Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles						eles			
Matte Tin (Sn) - annealed		CU	CU Alloy 1				260	60 C		30	seconds	3		
omments														
vel 1 - maximun	n time at peak temperature	e during sold	ering is 10-30	0 seconds										
or more informs	ation regarding material co	omposition n	lease refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Isability and the Company's remedies for issues that arise regarding information the Supplier pro											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-6_									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	2.98	mg	Supplier	Zinc (Zn)	7440-66-6		0.0036	mg
			Supplier	Iron (Fe)	7439-89-6		0.07	mg
			Supplier	Copper (Cu)	7440-50-8		2.9055	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0009	mg
Die	0.47	mg	Supplier	Silicon (Si)	7440-21-3		0.47	mg
Die Attach Solder	0.79	mg	Supplier	Silver (Ag)	7440-22-4		0.0198	mg
			A	Lead (Pb)	7439-92-1	7a	0.7308	mg
			Supplier	Tin (Sn)	7440-31-5		0.0395	mg
Lead Frame	12.41	mg	Supplier	Silver (Ag)	7440-22-4		0.1353	mg
			Supplier	Iron (Fe)	7439-89-6		0.0174	mg
			Supplier	Copper (Cu)	7440-50-8		12.2536	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0037	mg
Mold Compound-Black	15.0	mg		Epoxy resin	proprietary data		1.125	mg
			Supplier	Phenolic Resin	Proprietary Data		0.375	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.125	mg
			Supplier	Carbon Black (C)	1333-86-4		0.075	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		12.3	mg
Plating	0.6	mg	Supplier	Tin (Sn)	7440-31-5		0.6	mg